PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5258447

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SUSUMU MAEDA	11/05/2018
HIRONORI BANBA	11/05/2018
HARUO SUDO	11/05/2018
HIDEYUKI OKAMURA	11/09/2018
KOJI ARAKI	11/05/2018
KOJI SUEOKA	11/13/2018
KOZO NAKAMURA	11/10/2018

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16305680

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	SARAH PEDERSEN
SIGNATURE:	/SARAH PEDERSEN/
DATE SIGNED:	11/29/2018

Total Attachments: 3
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source=executed assignment#page3.tif

Wenderoth, Lind & Ponack, LLP
Attorney Docket No.: ______________

COMBINED DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION

Title of Invention	THERMAL PROCESSING METHOD FOR SILICON WAFER

DECLARATION

As a below named inventor, I hereby declare that:

This declaration
is directed to:

☐ The attached application, or

☒ United States application or PCT international application
number PCT/JP2017/011721 filed on March 23, 2017.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: "A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56."

ASSIGNMENT

In consideration of the sum of One Dollar ($1.00) and other good and valuable consideration paid, I hereby sell and assign to

GLOBALWAFERS JAPAN CO., LTD.
(Name of Assignee)

of **6-861-5, Seiro-machi Higashiko, Kitakanbara-gun, Niigata, Japan**
(Address of Assignee)

(hereinafter designated as the Assignee) my entire right, title and interest for the United States as defined in 35 USC 100, for any invention set forth in the above-identified application.

I agree to execute all papers necessary in connection with this application for patent in the USPTO for the invention, and any continuation, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

I agree to execute all papers necessary in connection with any post-grant proceeding which may occur in connection with this application or continuation, divisional or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such post-grant proceeding.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements, which includes the right to claim priority and the right to be granted a patent in any PCT Contracting State.

I agree to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

I hereby authorize and request the USPTO to issue any and all Letters Patents of the United States resulting from the application or any continuation, divisional or reissue applications thereof to the Assignee, as Assignee of my entire interest, and covenant that I have not executed, and will not execute, any agreement in conflict herewith.

First Inventor (Legal Name): Susumu MAEDA

Signature: Susumu Maeda Date: Nov., 5th, 2018

Second Inventor (Legal Name): Hironori BANBA

Signature: Hironori Banba Date: Nov., 5th, 2018

Third Inventor (Legal Name): Haruo SUDO

Signature: Haruo Sudo Date: Nov., 5th, 2018

Fourth Inventor (Legal Name): Hideyuki OKAMURA

Signature: Hideyuki Okamura Date: Nov., 9th, 2018

Fifth Inventor (Legal Name): Koji ARAKI

Signature: Koji Araki Date: Nov, 5th, 2018

Sixth Inventor (Legal Name): Koji SUEOKA

Signature: Koji Sueoka Date: Nov. 13th, 201

Seventh Inventor (Legal Name): Kozo NAKAMURA

Signature: Kozo Nakamura Date: November 10th, 2018